PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5745869

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKAHIRO OKADA	07/11/2019
TADAAKI YUBA	07/11/2019
JUN UESHIMA	07/12/2019
SHINICHI TSUCHIDA	07/16/2019
KEN MATSUMOTO	07/16/2019

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO
Internal Address:	ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	2430014

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	16478292	

CORRESPONDENCE DATA

Fax Number: (312)803-4960

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: docketing@chiplawgroup.com

Correspondent Name: CHIP LAW GROUP
Address Line 1: 505 N LAKESHORE DR

Address Line 2: SUITE 250

Address Line 4: CHICAGO, ILLINOIS 60611

Total Attachments: 5	
DATE SIGNED:	09/30/2019
SIGNATURE:	/Pramod Chintalapoodi/
NAME OF SUBMITTER:	PRAMOD CHINTALAPOODI
ATTORNEY DOCKET NUMBER:	SP368279US00

Total Attachments: 5

PATENT REEL: 050567 FRAME: 0675

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DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention SYSTEM ARITHMETIC PROCESSING APPARATUS AND INFORMATION PROCESSING		
As the below named inventor, I hereby declare that:		
This declaration is directed to: The attached application, or		
United States application or PCT international application number PCT/JP2017/044910 filed on 2017/12/14		
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at		
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of		
acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;		
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights und/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filting of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;		
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR		
Inventor: TAKAHIRO OKADA Date: 2019/7/1		
Signature: Thalies Okarder		

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	ARITHMETIC PROCESSING APPARATUS AND INFORMATION PROCESSING SYSTEM	
As the below	named inventor, 1 hereby declare that:	
This declarati	When it is a first record in the contract of t	
	United States application or PCT international application number PCT/JP2017/044910 filed on 2017/12/14	
The above-id	entified application was made or authorized to be made by me.	
	I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at	
	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
acquiring all	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries:	
of which are legal represer in and to any any and all pi Convention I adheres, and United States Patent to said	EFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and nattives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to riority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters I ASSIGNEE, as the assignee of the whole right, title and interest thereto;	
designee, as remuneration	r agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further i, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of ales and countries foreign thereto;	
application fo	r agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for or foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;	
And I further agree that ASSIGNEE will, upon its request, he provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby this assignment	covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with and sale.	
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NA	ME OF INVENTOR	
invemor:	TADAAKI YUBA Date: 20/9 07.//	
Signature:	Tadaoki Yuba	

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention SYSTEM		
As the below named inventor, I hereby declare that:		
This declaration		
United States application or PCT international application number PCT/JP2017/044910 filed on 2017/12/14		
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at		
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of		
acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;		
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer into said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the international Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the fifting of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:		
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR		
Inventor: JUN UESHIMA Date: July 12, 2019		
Signature: Um Talania		

Attorney Docket No.: Sony Ref. No.: SP368279US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	ARITHMETIC PROCESSING APPARATUS AND INFORMATION PROCESSING SYSTEM	
As the below named inventor, I hereby declare that:		
This declarate is directed to:	The assumed ment and a me	
	United States application or PCT international application number PCT/JP2017/044910 filed on	
The above-id	lentified application was made or authorized to be made by me.	
I believe that WHEREAS	t I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION with offices at	
4-14-1 A	Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar ion which may be granted therefor in the United States and in any and all foreign countries;	
of which are legal represer in and to any any and all p Convention 3 adheres, and United States Patent to said	EFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency believely acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and matives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and y and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the sand countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters dia ASSIGNEE, as the assignee of the whole right, title and interest thereto:	
designee, as remaneration	ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further n, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of tates and countries foreign thereto;	
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall bereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NA	ME OF INVENTOR	
Inventor:	SHINICHI TSUCHIDA Date: 20/9.07/6	
Signature:	shimichi Tsuchida	

Attorney Docket No.: Sony Ref. No.: SP368279US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention SYSTEM ARITHMETIC PROCESSING APPARATUS AND INFORMA	TION PROCESSING	
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This declaration is directed to: The attached application, or		
United States application or PCT international application number PCT/filed on 2017/12/14	JP2017/044910	
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application whereas, SONY SEMICONDUCTOR SOLUTIONS CORPORATION	, with offices at	
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter ret acquiring all interest in, to and under said invention, said application disclosing the invention and in, to a legal protection which may be granted therefor in the United States and in any and all foreign countries;	erred to as ASSIGNEE), is destrous of and under any Letters Patent or similar	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;		
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale:		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR	. 187 . A. 8 E	
Inventor: KEN MATSUMOTO Date: 20	019.09.16	
Signature: KEN MATSUMOTO		

PATENT REEL: 050567 FRAME: 0681

RECORDED: 09/30/2019